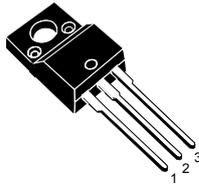
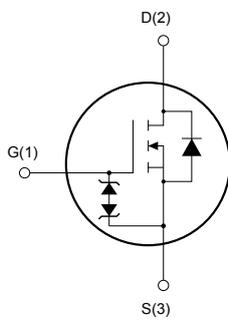


N-channel 650 V, 0.60 Ω typ., 7 A MDmesh M2 Power MOSFET in a TO-220FP ultra narrow leads package



TO-220FP
ultra narrow leads



AM15572v1_no_tab



Product status link

[STFU11N65M2](#)

Product summary

| | |
|-------------------|--------------------------------|
| Order code | STFU11N65M2 |
| Marking | 11N65M2 |
| Package | TO-220FP ultra narrow leads |
| Packing | Tube |

Features

| Order code | V_{DS} | $R_{DS(on)}$ max. | I_D |
|-------------|----------|-------------------|-------|
| STFU11N65M2 | 650 V | 0.68 Ω | 7 A |

- Extremely low gate charge
- Excellent output capacitance (C_{OSS}) profile
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using MDmesh M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|------------|------------------|
| V_{GS} | Gate-source voltage | ± 25 | V |
| $I_D^{(1)}$ | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$ | 7 | A |
| | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 4.4 | |
| $I_{DM}^{(2)}$ | Drain current (pulsed) | 28 | A |
| P_{TOT} | Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$ | 25 | W |
| $dv/dt^{(3)}$ | Peak diode recovery voltage slope | 15 | V/ns |
| $dv/dt^{(4)}$ | MOSFET dv/dt ruggedness | 50 | |
| V_{ISO} | Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1\text{ s}$, $T_C = 25\text{ }^\circ\text{C}$) | 2.5 | kV |
| T_{stg} | Storage temperature range | -55 to 150 | $^\circ\text{C}$ |
| T_J | Operating junction temperature range | | |

- Limited by maximum junction temperature.
- Pulse width limited by T_J max.
- $I_{SD} \leq 7\text{ A}$, $di/dt = 400\text{ A}/\mu\text{s}$, $V_{DS}(\text{peak}) < V_{(BR)DSS}$, $V_{DD} = 400\text{ V}$.
- $V_{DS} \leq 520\text{ V}$.

Table 2. Thermal data

| Symbol | Parameter | Value | Unit |
|----------------|-------------------------------------|-------|---------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case | 5 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-amb}$ | Thermal resistance junction-ambient | 62.5 | |

Table 3. Avalanche characteristics

| Symbol | Parameter | Value | Unit |
|----------|--|-------|------|
| I_{AR} | Avalanche current, repetitive or not repetitive (pulse width limited by T_J max) | 1.5 | A |
| E_{AS} | Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$) | 110 | mJ |

2 Electrical characteristics

($T_C = 25\text{ °C}$ unless otherwise specified)

Table 4. Static

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------------------|---|------|------|----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$ | 650 | | | V |
| I_{DSS} | Zero gate voltage drain current | $V_{GS} = 0\text{ V}$, $V_{DS} = 650\text{ V}$ | | | 1 | μA |
| | | $V_{GS} = 0\text{ V}$, $V_{DS} = 650\text{ V}$, $T_C = 125\text{ °C}^{(1)}$ | | | 100 | |
| I_{GSS} | Gate-body leakage current | $V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$ | | | ± 10 | μA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$ | 2 | 3 | 4 | V |
| $R_{DS(on)}$ | Static drain-source on-resistance | $V_{GS} = 10\text{ V}$, $I_D = 3.5\text{ A}$ | | 0.60 | 0.68 | Ω |

1. Defined by design, not subject to production test.

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------------------|-------------------------------|---|------|------|------|---------------|
| C_{iss} | Input capacitance | $V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$ | - | 410 | - | μF |
| C_{oss} | Output capacitance | | - | 20 | - | |
| C_{rss} | Reverse transfer capacitance | | - | 0.9 | - | |
| $C_{oss\text{ eq.}}^{(1)}$ | Equivalent output capacitance | $V_{DS} = 0\text{ to }520\text{ V}$, $V_{GS} = 0\text{ V}$ | - | 43 | - | μF |
| R_G | Intrinsic gate resistance | $f = 1\text{ MHz}$, $I_D = 0\text{ A}$ | - | 6.4 | - | Ω |
| Q_g | Total gate charge | $V_{DD} = 520\text{ V}$, $I_D = 7\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 14. Test circuit for gate charge behavior) | - | 12.5 | - | nC |
| Q_{gs} | Gate-source charge | | - | 3.2 | - | |
| Q_{gd} | Gate-drain charge | | - | 5.8 | - | |

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 325\text{ V}$, $I_D = 3.5\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ | - | 9.5 | - | ns |
| t_r | Rise time | | - | 7.5 | - | |
| $t_{d(off)}$ | Turn-off delay time | (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform) | - | 26 | - | |
| t_f | Fall time | | - | 15 | - | |

Table 7. Source-drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|---|------|------|------|---------------|
| I_{SD} | Source-drain current | | - | | 7 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | - | | 28 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $V_{GS} = 0\text{ V}$, $I_{SD} = 7\text{ A}$ | - | | 1.6 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 7\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times) | - | 318 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 2.5 | | μC |
| I_{RRM} | Reverse recovery current | $I_{SD} = 7\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times) | - | 15.5 | | A |
| t_{rr} | Reverse recovery time | | - | 437 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 3.2 | | μC |
| I_{RRM} | Reverse recovery current | | - | 15 | | A |

1. Pulse width is limited by safe operating area.
2. Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

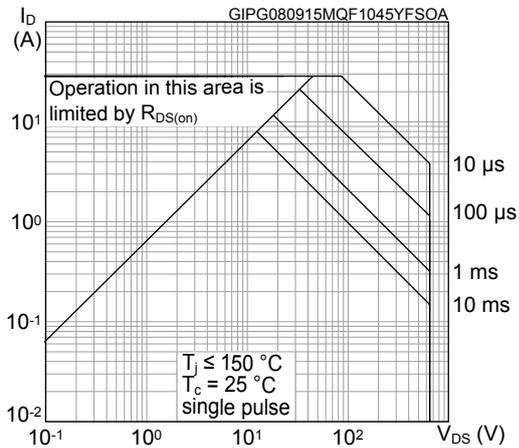


Figure 2. Thermal impedance

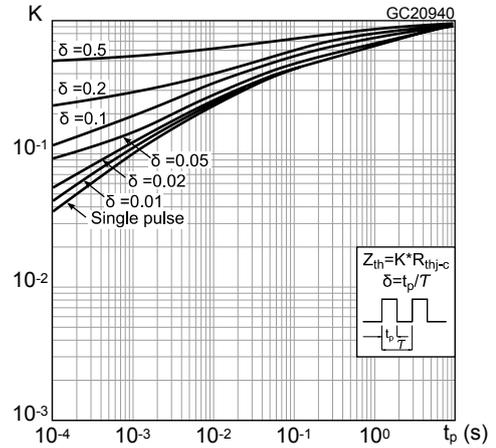


Figure 3. Output characteristics

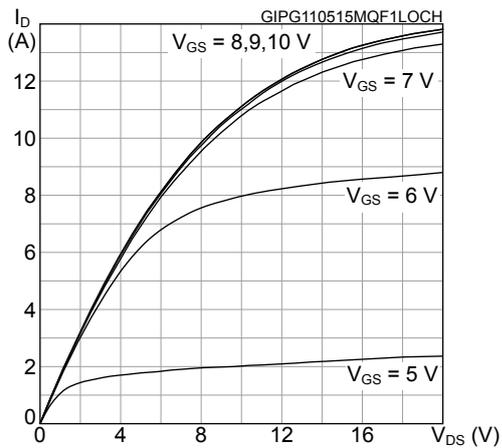


Figure 4. Transfer characteristics

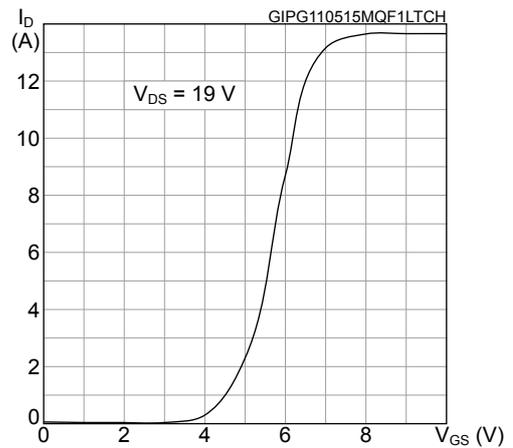


Figure 5. Gate charge vs gate-source voltage

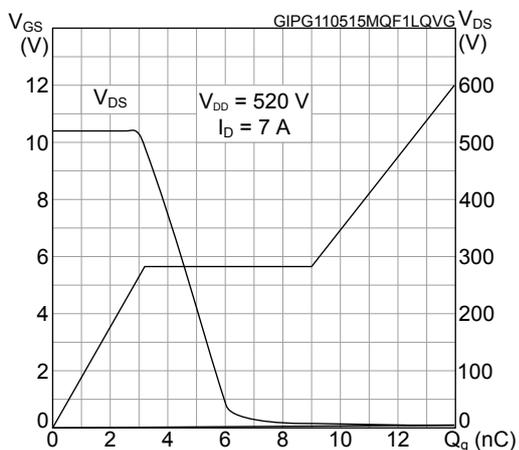


Figure 6. Static drain-source on-resistance

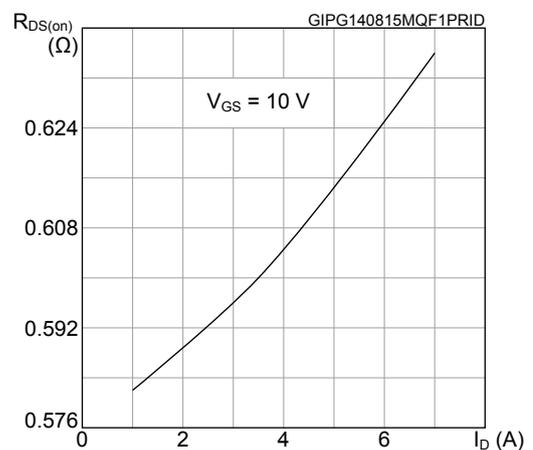


Figure 7. Capacitance variations

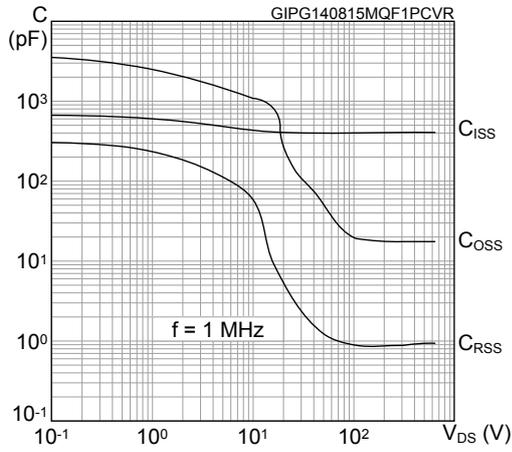


Figure 8. Normalized gate threshold voltage vs temperature

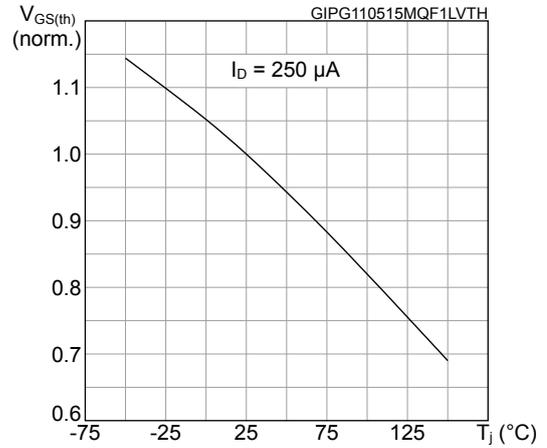


Figure 9. Normalized on-resistance vs temperature

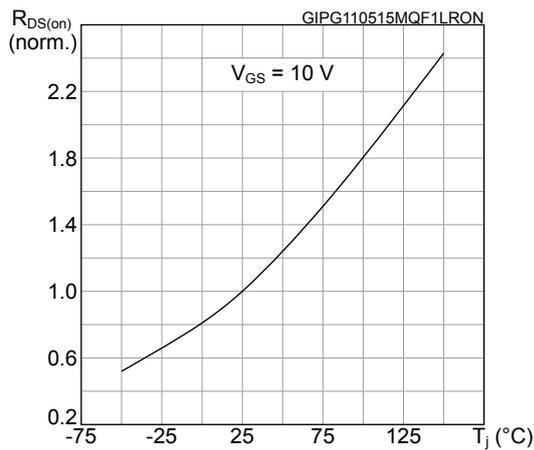


Figure 10. Normalized V_{(BR)DSS} vs temperature

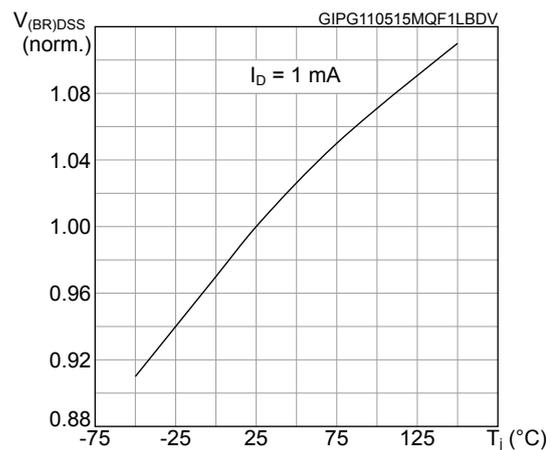


Figure 11. Output capacitance stored energy

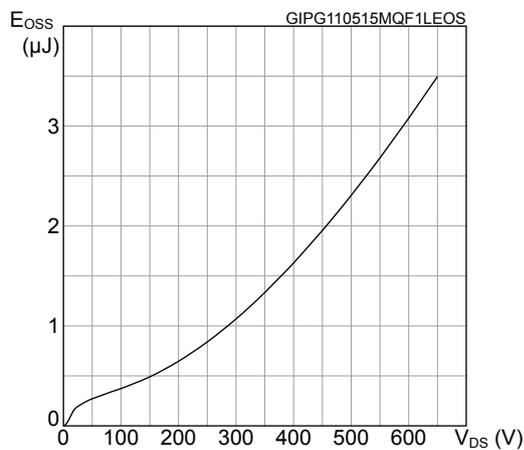
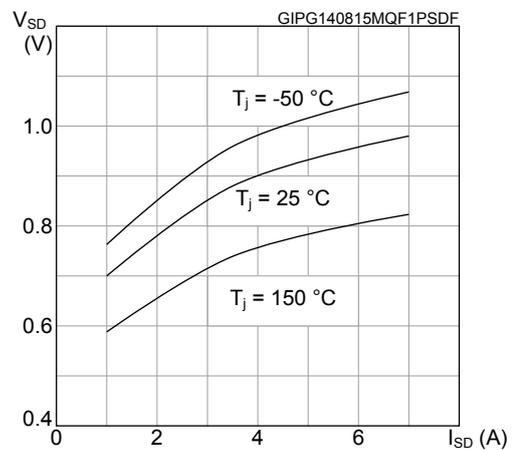


Figure 12. Source-drain diode forward characteristics

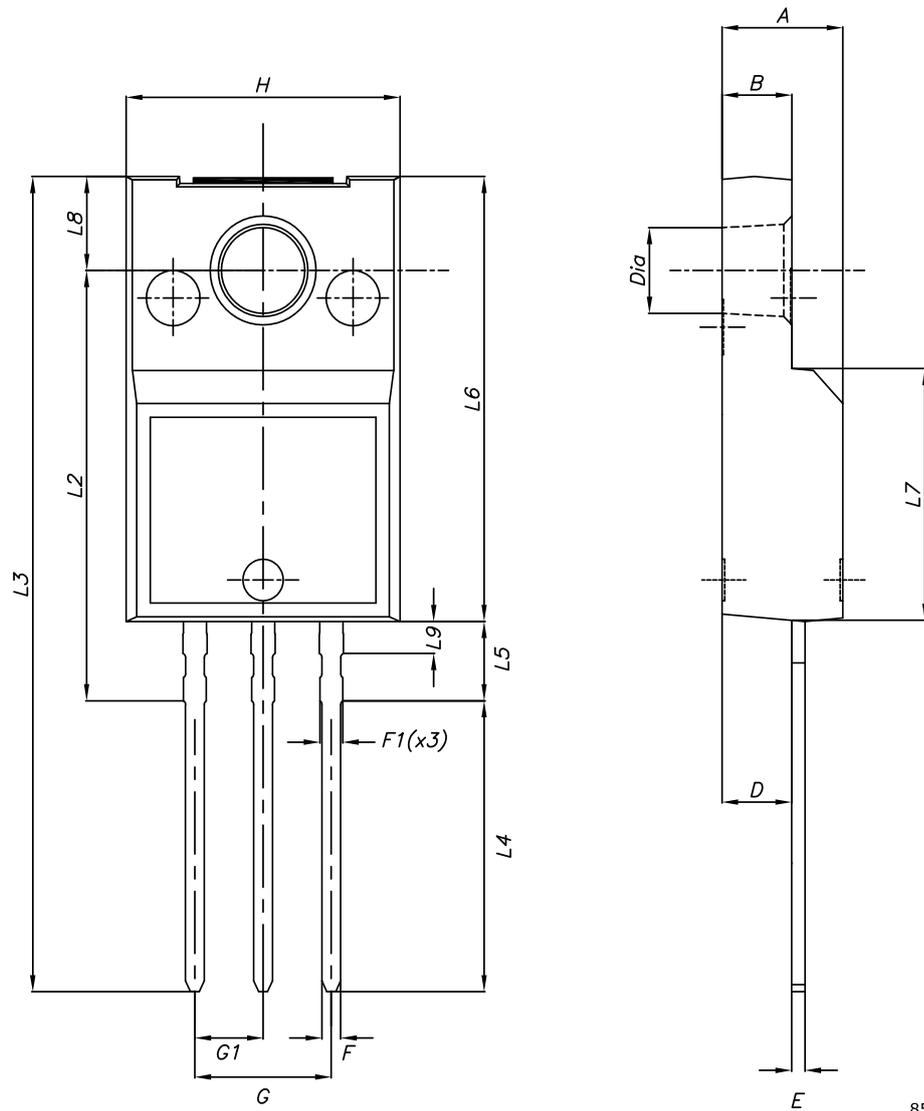


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-220FP ultra narrow leads package information

Figure 19. TO-220FP ultra narrow leads package outline



8576148_2

Table 8. TO-220FP ultra narrow leads mechanical data

| Dim. | mm | | |
|------|-------|------|-------|
| | Min. | Typ. | Max. |
| A | 4.40 | | 4.60 |
| B | 2.50 | | 2.70 |
| D | 2.50 | | 2.75 |
| E | 0.45 | | 0.60 |
| F | 0.65 | | 0.75 |
| F1 | - | | 0.90 |
| G | 4.95 | | 5.20 |
| G1 | 2.40 | 2.54 | 2.70 |
| H | 10.00 | | 10.40 |
| L2 | 15.10 | | 15.90 |
| L3 | 28.50 | | 30.50 |
| L4 | 10.20 | | 11.00 |
| L5 | 2.50 | | 3.10 |
| L6 | 15.60 | | 16.40 |
| L7 | 9.00 | | 9.30 |
| L8 | 3.20 | | 3.60 |
| L9 | - | | 1.30 |
| Dia. | 3.00 | | 3.20 |

Revision history

Table 9. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 03-Apr-2017 | 1 | First release. |
| 25-Jun-2019 | 2 | Updated Table 1. Absolute maximum ratings . Updated Section 2 Electrical characteristics . Minor text changes. |

Contents

| | | |
|------------|--|-----------|
| 1 | Electrical ratings | 2 |
| 2 | Electrical characteristics | 3 |
| 2.1 | Electrical characteristics (curves) | 5 |
| 3 | Test circuits | 7 |
| 4 | Package information | 8 |
| 4.1 | TO-220FP ultra narrow leads package information | 8 |
| | Revision history | 10 |

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2019 STMicroelectronics – All rights reserved

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [MOSFET](#) category:

Click to view products by [STMicroelectronics](#) manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [IRFD120](#) [JANTX2N5237](#) [2N7000](#) [FCA20N60_F109](#) [FDZ595PZ](#) [2SK2545\(Q,T\)](#) [405094E](#) [423220D](#)
[TPCC8103,L1Q\(CM](#) [MIC4420CM-TR](#) [VN1206L](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [SSM6J414TU,LF\(T](#) [751625C](#)
[IPS70R2K0CEAKMA1](#) [BUK954R8-60E](#) [DMN3404LQ-7](#) [NTE6400](#) [SQJ402EP-T1-GE3](#) [2SK2614\(TE16L1,Q\)](#) [2N7002KW-FAI](#)
[DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [ECH8691-TL-W](#) [FCAB21350L1](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE221](#) [NTE2384](#)
[NTE2903](#) [NTE2941](#) [NTE2945](#) [NTE2946](#) [NTE2960](#) [NTE2967](#) [NTE2969](#) [NTE2976](#) [NTE455](#) [NTE6400A](#) [NTE2910](#) [NTE2916](#) [NTE2956](#)
[NTE2911](#) [US6M2GTR](#) [TK10A80W,S4X\(S](#) [SSM6P69NU,LF](#)